

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shih-Chi Fu</td> <td>01/24/2006</td> </tr> <tr> <td>Gwo-Yuh Shiau</td> <td>02/07/2006</td> </tr> <tr> <td>Liang-Lung Yao</td> <td>03/31/2006</td> </tr> <tr> <td>Yuan-Chih Hsieh</td> <td>01/24/2006</td> </tr> <tr> <td>Feng-Jia Shiu</td> <td>01/24/2006</td> </tr> </tbody> </table>		Name	Execution Date	Shih-Chi Fu	01/24/2006	Gwo-Yuh Shiau	02/07/2006	Liang-Lung Yao	03/31/2006	Yuan-Chih Hsieh	01/24/2006	Feng-Jia Shiu	01/24/2006
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Feng-Jia Shiu	01/24/2006												
RECEIVING PARTY DATA													
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.												
Street Address:	No. 8, Li-Hsin Road 6												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 2													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13044407</td> </tr> <tr> <td>Application Number:</td> <td>12634080</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13044407	Application Number:	12634080						
Property Type	Number												
Application Number:	13044407												
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CORRESPONDENCE DATA													
Fax Number:	(214)200-0853												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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ATTORNEY DOCKET NUMBER:	24061.1761, 24061.1382												

OP \$80.00 13044407

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**PATENT
 REEL: 025941 FRAME: 0246**

NAME OF SUBMITTER:

Rachel L.I. Davis

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|---------------------------------------------------------------------------------------|
| (1) | Shih-Chi Fu | of | 4F, No. 41, Lane 87, Fuyang Street
Sinyi District, Taipei City 110, Taiwan, R.O.C. |
| (2) | Gwo-Yuh Shiau | of | No. 6, Lane 267, Shihpin Road
Hsinchu City 300, Taiwan, R.O.C. |
| (3) | Liang-Lung Yao | of | 3 F. No. 27, Lane 573, Pai-An Road
Taipei City, Taiwan, R.O.C. |
| (4) | Yuan-Chih Hsieh | of | 4F, No. 12, Lane 1007, Daxue Road
Hsinchu City 300, Taiwan, R.O.C. |
| (5) | Feng-Jia Shiu | of | 6F-3, No. 18, Alley 51, Lane 400,
Minghu Road
Hsinchu City 300, Taiwan, R.O.C. |

have invented certain improvements in

METHOD OF FABRICATING BACKSIDE ILLUMINATED IMAGE SENSOR

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on March 6, 2006 and assigned application number 11/369,054; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said

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Customer No.: 000042717

Invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Shih-Chi Fu

Residence Address: 4F, No. 41, Lane 87, Fuyang Street
Sinyi District, Taipei City 110, Taiwan, R.O.C.

Dated: Jan. 24, 2006

Shih-Chi Fu
Inventor Signature

Inventor Name: Gwo-Yuh Shiau

Residence Address: No. 6, Lane 267, Shihpin Road
Hsinchu City 300, Taiwan, R.O.C.

Dated: Feb. 7, 2006

Gwo-Yuh Shiau
Inventor Signature

Inventor Name: Liang-Lung Yao

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Dated: Mar. 31, 2006

Liang-Lung Yao
Inventor Signature

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Inventor Name: Yuan-Chih Hsieh

Residence Address: 4F, No. 12, Lane 1007, Daxue Road
Hsinchu City 300, Taiwan, R.O.C.

Dated: Jan. 24, 2006

Yuan-Chih Hsieh
Inventor Signature

Inventor Name: Feng-Jia Shiu

Residence Address: 6F-3, No. 18, Alley 51, Lane 400
Minghu Road
Hsinchu City 300, Taiwan, R.O.C.

Dated: Jan. 24, 2006

Feng-Jia Shiu
Inventor Signature